

## Automotive P-Channel 30 V (D-S) 175 °C MOSFET

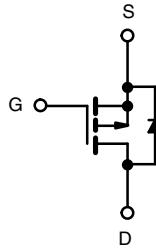
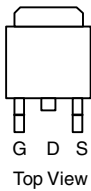


**RoHS**  
COMPLIANT  
HALOGEN  
**FREE**

| PRODUCT SUMMARY                                |        |
|--|--------|
| $V_{DS}$ (V)                                   | - 30   |
| $R_{DS(on)}$ ( $\Omega$ ) at $V_{GS} = -10$ V  | 0.0070 |
| $R_{DS(on)}$ ( $\Omega$ ) at $V_{GS} = -4.5$ V | 0.0110 |
| $I_D$ (A)                                      | - 50   |
| Configuration                                  | Single |

### FEATURES

- TrenchFET® Power MOSFET
- Package with Low Thermal Resistance
- 100 %  $R_g$  and UIS Tested
- AEC-Q101 Qualified<sup>d</sup>
- Material categorization:  
For definitions of compliance please see [www.vishay.com/doc?99912](http://www.vishay.com/doc?99912)

**TO-263**


P-Channel MOSFET

### ORDERING INFORMATION

|                                 |                 |
|---------------------------------|-----------------|
| Package                         | TO-263          |
| Lead (Pb)-free and Halogen-free | SQM50P03-07-GE3 |

### ABSOLUTE MAXIMUM RATINGS ( $T_C = 25$ °C, unless otherwise noted)

| PARAMETER   | SYMBOL         | LIMIT          | UNIT |
|---|----------------|----------------|------|
| Drain-Source Voltage                                      | $V_{DS}$       | - 30           | V    |
| Gate-Source Voltage                                       | $V_{GS}$       | $\pm 20$       |      |
| Continuous Drain Current <sup>a</sup>                     | $I_D$          | $T_C = 25$ °C  | - 50 |
|   |                | $T_C = 125$ °C | - 50 |
| Continuous Source Current (Diode Conduction) <sup>a</sup> | $I_S$          | - 50           | A    |
| Pulsed Drain Current <sup>b</sup>                         | $I_{DM}$       | - 200          |      |
| Single Pulse Avalanche Current                            | $I_{AS}$       | - 50           |      |
| Single Pulse Avalanche Energy                             | $E_{AS}$       | 125            | mJ   |
| Maximum Power Dissipation <sup>b</sup>                    | $P_D$          | $T_C = 25$ °C  | 150  |
|   |                | $T_C = 125$ °C | 50   |
| Operating Junction and Storage Temperature Range          | $T_J, T_{stg}$ | - 55 to + 175  | °C   |

### THERMAL RESISTANCE RATINGS

| PARAMETER                | SYMBOL     | LIMIT | UNIT |
|--------------------------|------------|-------|------|
| Junction-to-Ambient      | $R_{thJA}$ | 40    | °C/W |
| Junction-to-Case (Drain) | $R_{thJC}$ | 1     |      |

#### Notes

- Package limited.
- Pulse test; pulse width  $\leq 300$   $\mu$ s, duty cycle  $\leq 2$  %.
- When mounted on 1" square PCB (FR-4 material).
- Parametric verification ongoing.



| SPECIFICATIONS ( $T_C = 25\text{ }^\circ\text{C}$ , unless otherwise noted) |              |   |  |      |        |           |               |
|---|--------------|---|--|------|--------|-----------|---------------|
| PARAMETER   | SYMBOL       | TEST CONDITIONS   |  | MIN. | TYP.   | MAX.      | UNIT          |
| <b>Static</b>   |              |   |  |      |        |           |               |
| Drain-Source Breakdown Voltage  | $V_{DS}$     | $V_{GS} = 0\text{ V}, I_D = -250\text{ }\mu\text{A}$  |  | -30  | -      | -         | V             |
| Gate-Source Threshold Voltage   | $V_{GS(th)}$ | $V_{DS} = V_{GS}, I_D = -250\text{ }\mu\text{A}$  |  | -1.5 | -2.0   | -2.5      |               |
| Gate-Source Leakage   | $I_{GSS}$    | $V_{DS} = 0\text{ V}, V_{GS} = \pm 20\text{ V}$   |  | -    | -      | $\pm 100$ | nA            |
| Zero Gate Voltage Drain Current   | $I_{DSS}$    | $V_{GS} = 0\text{ V}$   | $V_{DS} = -30\text{ V}$                                  | -    | -      | -1        | $\mu\text{A}$ |
|   |              | $V_{GS} = 0\text{ V}$   | $V_{DS} = -30\text{ V}, T_J = 125\text{ }^\circ\text{C}$ | -    | -      | -50       |               |
|   |              | $V_{GS} = 0\text{ V}$   | $V_{DS} = -30\text{ V}, T_J = 175\text{ }^\circ\text{C}$ | -    | -      | -250      |               |
| On-State Drain Current <sup>a</sup>   | $I_{D(on)}$  | $V_{GS} = -10\text{ V}$   | $V_{DS} \leq -5\text{ V}$                                | -120 | -      | -         | A             |
| Drain-Source On-State Resistance <sup>a</sup>                               | $R_{DS(on)}$ | $V_{GS} = -10\text{ V}$   | $I_D = -30\text{ A}$                                     | -    | 0.0050 | 0.0070    | $\Omega$      |
|   |              | $V_{GS} = -10\text{ V}$   | $I_D = -30\text{ A}, T_J = 125\text{ }^\circ\text{C}$    | -    | -      | 0.0102    |               |
|   |              | $V_{GS} = -10\text{ V}$   | $I_D = -30\text{ A}, T_J = 175\text{ }^\circ\text{C}$    | -    | -      | 0.0118    |               |
|   |              | $V_{GS} = -4.5\text{ V}$  | $I_D = -20\text{ A}$                                     | -    | 0.0089 | 0.0110    |               |
| Forward Transconductance <sup>b</sup>                                       | $g_{fs}$     | $V_{DS} = -15\text{ V}, I_D = -30\text{ A}$   |  | -    | 62     | -         | S             |
| <b>Dynamic<sup>b</sup></b>  |              |   |  |      |        |           |               |
| Input Capacitance   | $C_{iss}$    | $V_{GS} = 0\text{ V}$   | $V_{DS} = -25\text{ V}, f = 1\text{ MHz}$                | -    | 4304   | 5380      | $\mu\text{F}$ |
| Output Capacitance  | $C_{oss}$    |   |  | -    | 764    | 955       |               |
| Reverse Transfer Capacitance  | $C_{rss}$    |   |  | -    | 680    | 850       |               |
| Total Gate Charge <sup>c</sup>  | $Q_g$        | $V_{GS} = -10\text{ V}$   | $V_{DS} = -15\text{ V}, I_D = -75\text{ A}$              | -    | 103.5  | 155       | nC            |
| Gate-Source Charge <sup>c</sup>   | $Q_{gs}$     |   |  | -    | 14.3   | -         |               |
| Gate-Drain Charge <sup>c</sup>  | $Q_{gd}$     |   |  | -    | 26.9   | -         |               |
| Gate Resistance   | $R_g$        | f = 1 MHz   |  | 1.4  | 2.85   | 4.3       | $\Omega$      |
| Turn-On Delay Time <sup>c</sup>   | $t_{d(on)}$  | $V_{DD} = -15\text{ V}, R_L = 0.2\text{ }\Omega$<br>$I_D \cong -75\text{ A}, V_{GEN} = -10\text{ V}, R_g = 1\text{ }\Omega$ |  | -    | 11     | 17        | ns            |
| Rise Time <sup>c</sup>  | $t_r$        |   |  | -    | 10     | 15        |               |
| Turn-Off Delay Time <sup>c</sup>  | $t_{d(off)}$ |   |  | -    | 63     | 95        |               |
| Fall Time <sup>c</sup>  | $t_f$        |   |  | -    | 26     | 39        |               |
| <b>Source-Drain Diode Ratings and Characteristics<sup>b</sup></b>           |              |   |  |      |        |           |               |
| Pulsed Current <sup>a</sup>   | $I_{SM}$     |   |  | -    | -      | -200      | A             |
| Forward Voltage   | $V_{SD}$     | $I_F = -45\text{ A}, V_{GS} = 0\text{ V}$   |  | -    | -0.9   | -1.5      | V             |

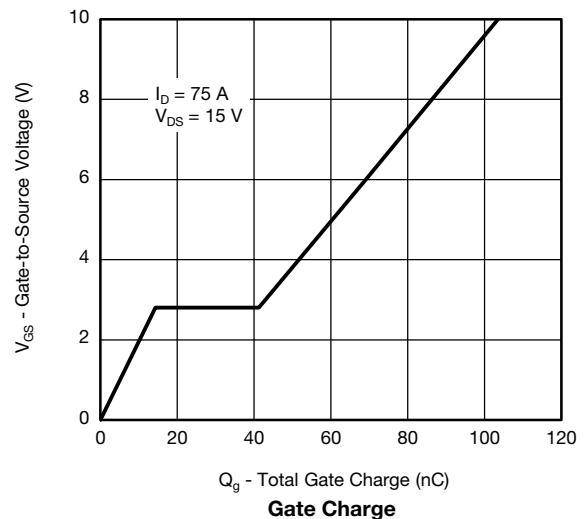
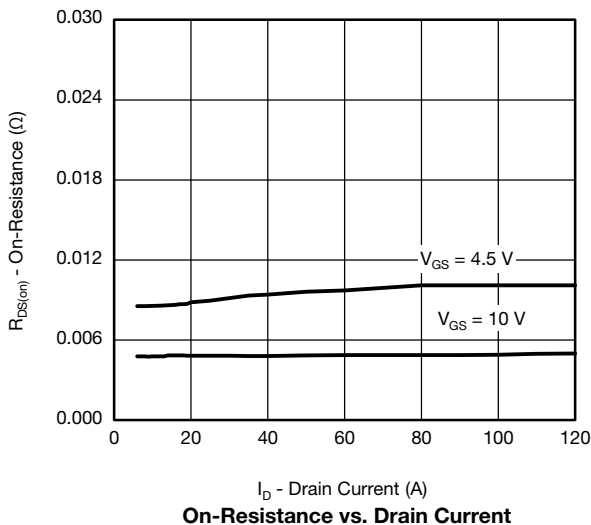
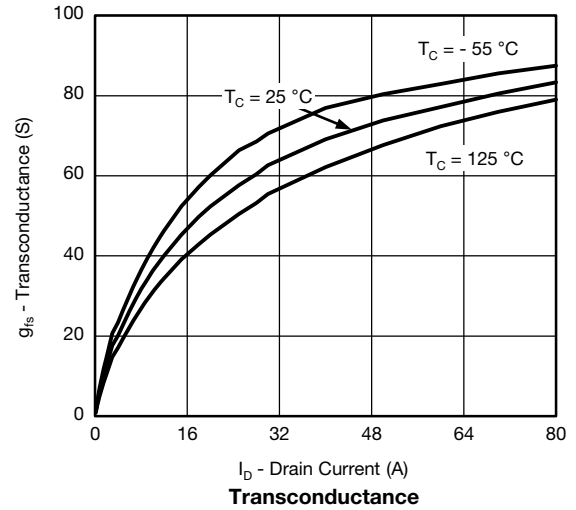
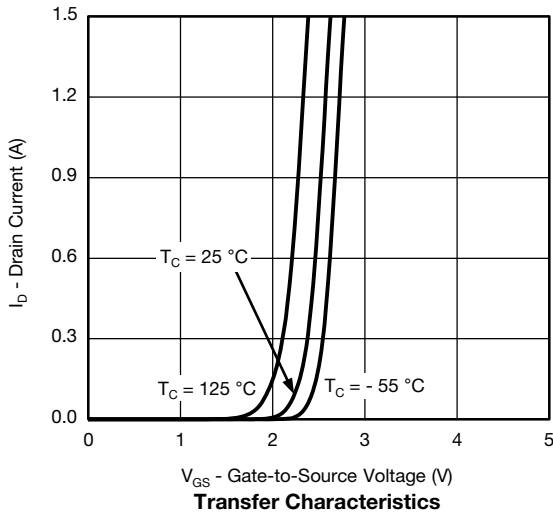
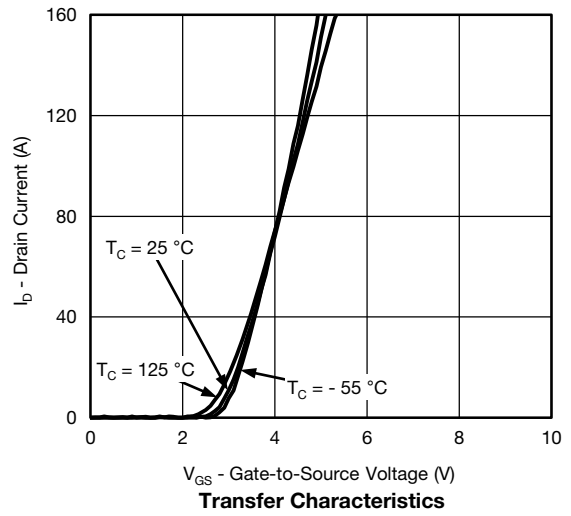
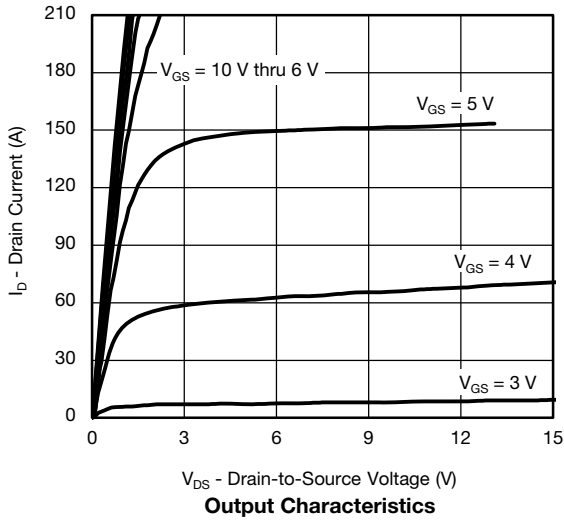
**Notes**

- a. Pulse test; pulse width  $\leq 300\text{ }\mu\text{s}$ , duty cycle  $\leq 2\%$ .  
b. Guaranteed by design, not subject to production testing.  
c. Independent of operating temperature.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

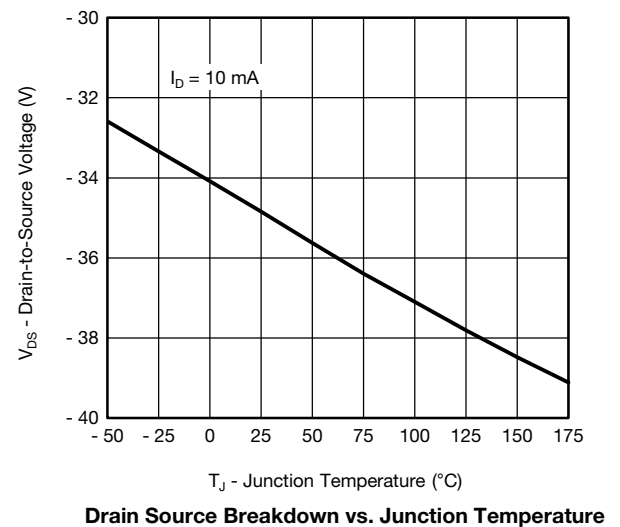
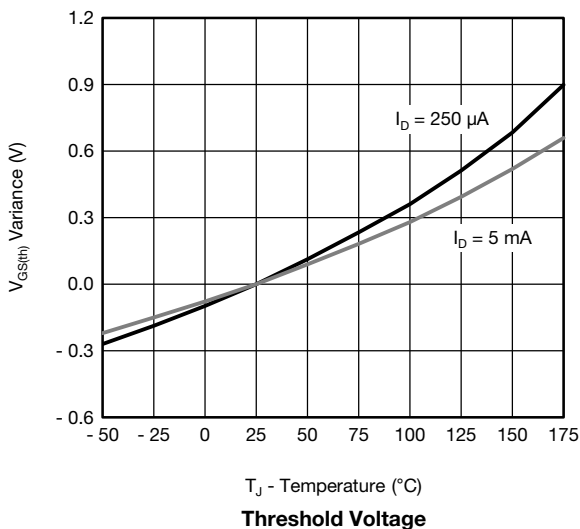
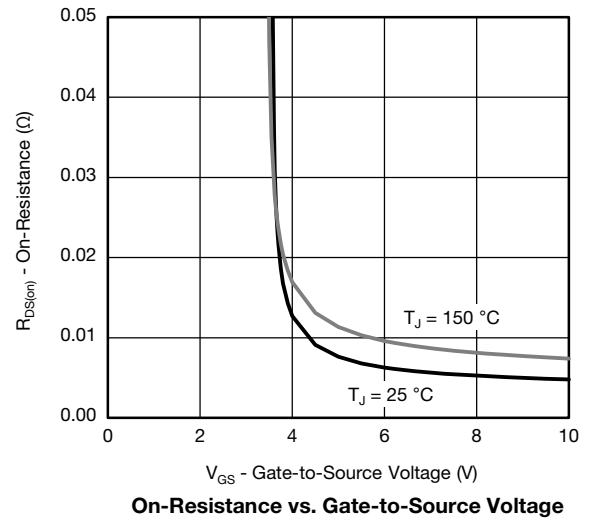
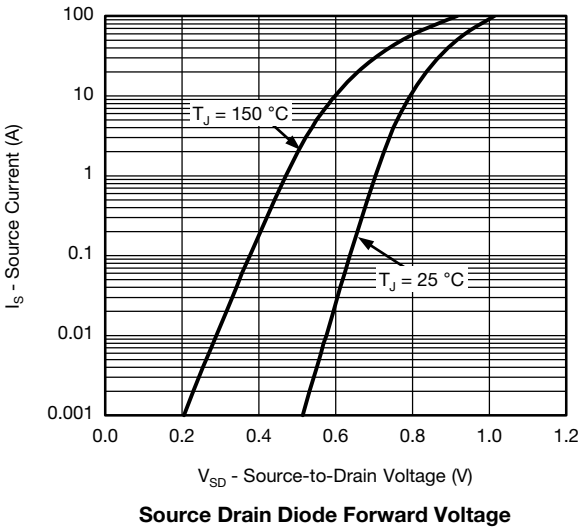
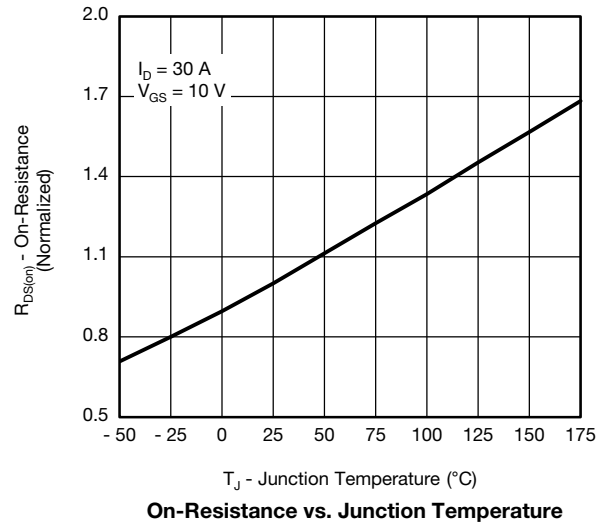
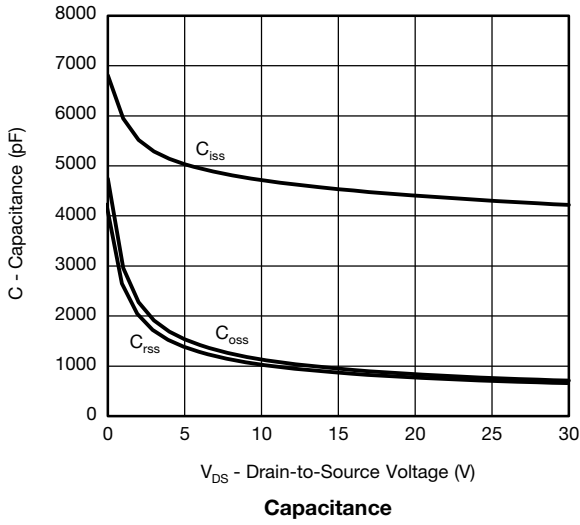


**TYPICAL CHARACTERISTICS** ( $T_A = 25\text{ }^\circ\text{C}$ , unless otherwise noted)



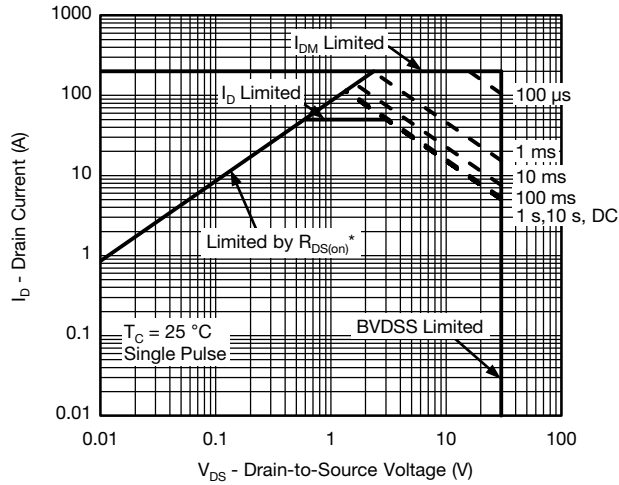


TYPICAL CHARACTERISTICS (T<sub>A</sub> = 25 °C, unless otherwise noted)



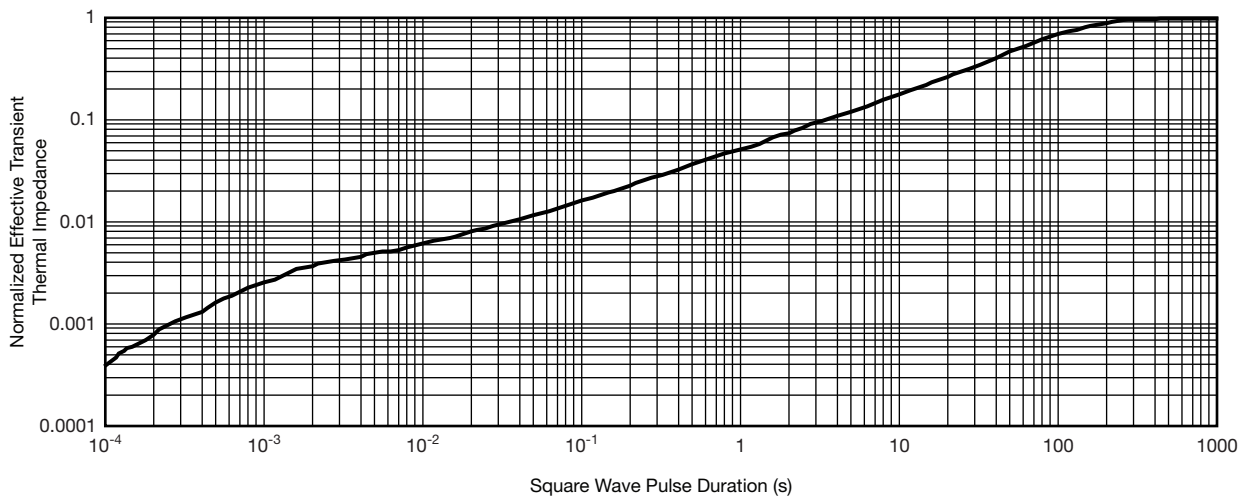


**THERMAL RATINGS** ( $T_A = 25\text{ }^\circ\text{C}$ , unless otherwise noted)



\*  $V_{GS} >$  minimum  $V_{GS}$  at which  $R_{DS(on)}$  is specified

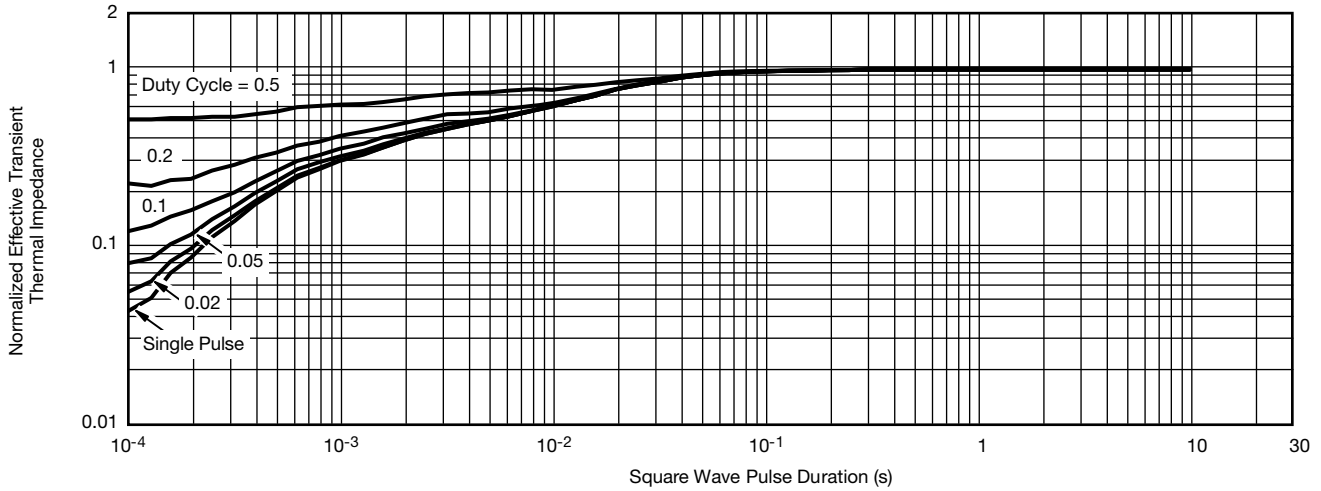
**Safe Operating Area**



**Normalized Thermal Transient Impedance, Junction-to-Ambient**



**THERMAL RATINGS** ( $T_A = 25\text{ }^\circ\text{C}$ , unless otherwise noted)



**Normalized Thermal Transient Impedance, Junction-to-Case**

**Note**

- The characteristics shown in the two graphs
  - Normalized Transient Thermal Impedance Junction-to-Ambient (25 °C)
  - Normalized Transient Thermal Impedance Junction-to-Case (25 °C)
 are given for general guidelines only to enable the user to get a “ball park” indication of part capabilities. The data are extracted from single pulse transient thermal impedance characteristics which are developed from empirical measurements. The latter is valid for the part mounted on printed circuit board - FR4, size 1" x 1" x 0.062", double sided with 2 oz. copper, 100 % on both sides. The part capabilities can widely vary depending on actual application parameters and operating conditions.

Vishay Siliconix maintains worldwide manufacturing capability. Products may be manufactured at one of several qualified locations. Reliability data for Silicon Technology and Package Reliability represent a composite of all qualified locations. For related documents such as package/tape drawings, part marking, and reliability data, see [www.vishay.com/ppg?67044](http://www.vishay.com/ppg?67044).

# TO-263 (D<sup>2</sup>PAK): 3-LEAD



| DIM.                            | INCHES     |       | MILLIMETERS |        |       |
|---------------------------------|------------|-------|-------------|--------|-------|
|                                 | MIN.       | MAX.  | MIN.        | MAX.   |       |
| A                               | 0.160      | 0.190 | 4.064       | 4.826  |       |
| b                               | 0.020      | 0.039 | 0.508       | 0.990  |       |
| b1                              | 0.020      | 0.035 | 0.508       | 0.889  |       |
| b2                              | 0.045      | 0.055 | 1.143       | 1.397  |       |
| c*                              | Thin lead  | 0.013 | 0.018       | 0.330  | 0.457 |
|                                 | Thick lead | 0.023 | 0.028       | 0.584  | 0.711 |
| c1                              | Thin lead  | 0.013 | 0.017       | 0.330  | 0.431 |
|                                 | Thick lead | 0.023 | 0.027       | 0.584  | 0.685 |
| c2                              | 0.045      | 0.055 | 1.143       | 1.397  |       |
| D                               | 0.340      | 0.380 | 8.636       | 9.652  |       |
| D1                              | 0.220      | 0.240 | 5.588       | 6.096  |       |
| D2                              | 0.038      | 0.042 | 0.965       | 1.067  |       |
| D3                              | 0.045      | 0.055 | 1.143       | 1.397  |       |
| D4                              | 0.044      | 0.052 | 1.118       | 1.321  |       |
| E                               | 0.380      | 0.410 | 9.652       | 10.414 |       |
| E1                              | 0.245      | -     | 6.223       | -      |       |
| E2                              | 0.355      | 0.375 | 9.017       | 9.525  |       |
| E3                              | 0.072      | 0.078 | 1.829       | 1.981  |       |
| e                               | 0.100 BSC  |       | 2.54 BSC    |        |       |
| K                               | 0.045      | 0.055 | 1.143       | 1.397  |       |
| L                               | 0.575      | 0.625 | 14.605      | 15.875 |       |
| L1                              | 0.090      | 0.110 | 2.286       | 2.794  |       |
| L2                              | 0.040      | 0.055 | 1.016       | 1.397  |       |
| L3                              | 0.050      | 0.070 | 1.270       | 1.778  |       |
| L4                              | 0.010 BSC  |       | 0.254 BSC   |        |       |
| M                               | -          | 0.002 | -           | 0.050  |       |
| ECN: T13-0707-Rev. K, 30-Sep-13 |            |       |             |        |       |
| DWG: 5843                       |            |       |             |        |       |

**Notes**

- Plane B includes maximum features of heat sink tab and plastic.
- No more than 25 % of L1 can fall above seating plane by max. 8 mils.
- Pin-to-pin coplanarity max. 4 mils.
- \*: Thin lead is for SUB, SYB.  
Thick lead is for SUM, SYM, SQM.
- Use inches as the primary measurement.
- This feature is for thick lead.

**RECOMMENDED MINIMUM PADS FOR D<sup>2</sup>PAK: 3-Lead**



Recommended Minimum Pads  
Dimensions in Inches/(mm)

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- Поставка более 17-ти миллионов наименований электронных компонентов;
- Поставка сложных, дефицитных, либо снятых с производства позиций;
- Оперативные сроки поставки под заказ (от 5 рабочих дней);
- Экспресс доставка в любую точку России;
- Техническая поддержка проекта, помощь в подборе аналогов, поставка прототипов;
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- Лицензия ФСБ на осуществление работ с использованием сведений, составляющих государственную тайну;
- Поставка специализированных компонентов (Xilinx, Altera, Analog Devices, Intersil, Interpoint, Microsemi, Aeroflex, Peregrine, Syfer, Eurofarad, Texas Instrument, Miteq, Cobham, E2V, MA-COM, Hittite, Mini-Circuits, General Dynamics и др.);

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- Подбор аналогов;
- Консультации по применению компонента;
- Поставка образцов и прототипов;
- Техническая поддержка проекта;
- Защита от снятия компонента с производства.



#### Как с нами связаться

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